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(71) Applicant *(for all designated States except US)*: **ADVANCED MICRO DEVICES, INC.** [US/US]; One AMD Place, Mail Stop 68, P.o. Box 3453, Sunnyvale, CA 94088-3453 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **SEIDEL, Robert** [DE/DE]; Eisenberger Str 4, 01127 Dresden (DE). **PETERS, Carsten** [DE/DE]; Fruehlingstr 5, 01099 Dresden (DE). **FEUSTEL, Frank** [DE/DE]; Am Doelzschgraben 10, 01187 Dresden (DE).

(74) Agent: **DRAKE, Paul, S.**; Advanced Micro Devices, Inc., 5204 East Ben White Boulevard, Mail Stop 562, Austin, TX 78741 (US).

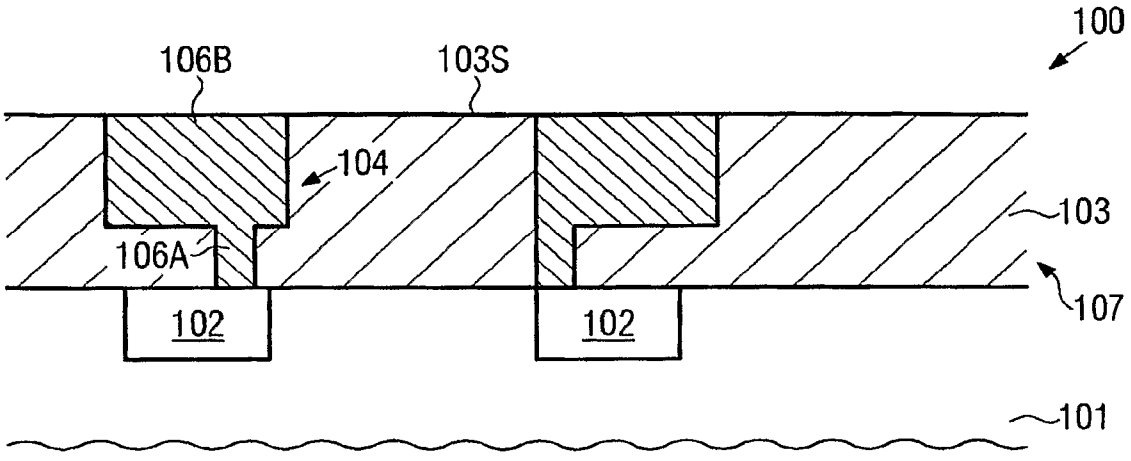
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(54) **Title:** A NANO IMPRINT TECHNIQUE WITH INCREASED FLEXIBILITY WITH RESPECT TO ALIGNMENT AND FEATURE SHAPING



(57) **Abstract:** By forming metallization structures on the basis of an imprint technique, in which via openings and trenches may be commonly formed, a significant reduction of process complexity may be achieved due to the omission of at least one further alignment process as required in conventional process techniques. Furthermore, the flexibility and efficiency of imprint lithography may be increased by providing appropriately designed imprint molds in order to provide via openings and trenches exhibiting an increased fill capability, thereby also improving the performance of the finally obtained metallization structures with respect to reliability, resistance against electromigration and the like.

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